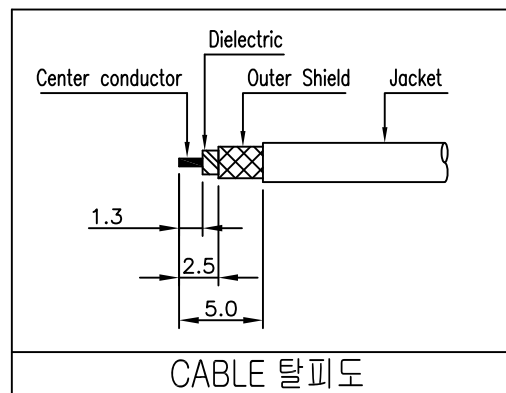
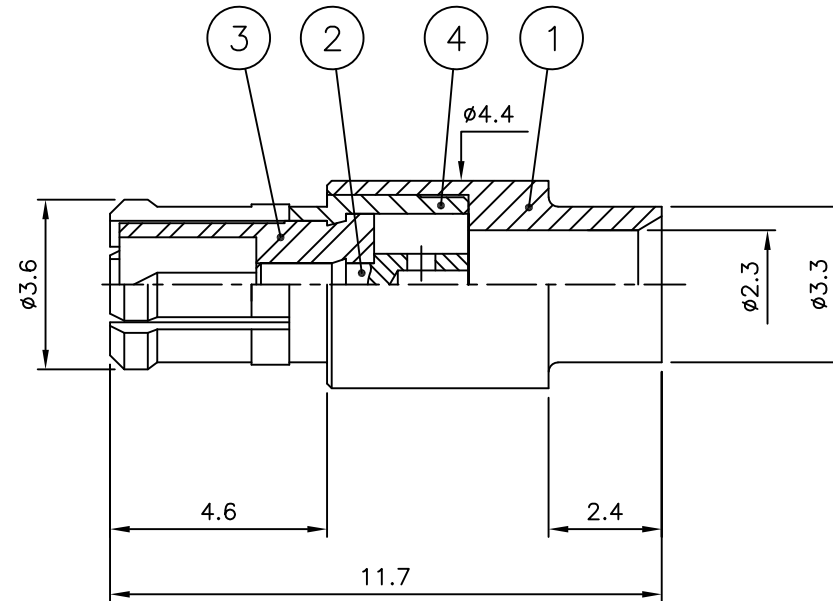


REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	S.Y.EUN	I.C.KIM	2018.04.17.
1	[설변No.201907-0008] 가공성 개선으로 인한 절연체 형상 변경	S.Y.EUN	I.C.KIM	2019.07.23.
2	작업성 개선으로 인한 JACK 및 PIN HOOK 추가	S.Y.EUN	S.H.KIM	2023.01.13.



2	4	JACK	1	BeCu C17300	Gold Plate	DJA00009-5/5 DJA00009-5/4
1	3	INSULATOR	1	TEFLON		DIN00059-N/1
2	2	CONTACT	1	MBsBD C3604BD-F	Gold Plate	DCT00060-5/2 DCT00060-5/1
	1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD04010-5/2
	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE

TOLERANCE	Decimal ±0.1	DATE 2023. 01. 13.		 RF & MICROWAVE TECHNOLOGY Tel : 82-32-347-8015 Fax : 82-32-347-8017	
	Angle ±1°	APPROVED BY	S.H.KIM		
MATERIAL —	CHECKED BY	TITLE MCX50 CABLE PS 85TP(50Ω)			
FINISH —	SCALE 6/1	UNIT mm		A4	DWG NO. CN00020-7/4
					REVISION 2